**Product End-of-Life Disassembly Instructions**

**Product Category:** Personal Computers

**Marketing Name / Model**
[List multiple models if applicable.]

Compaq CQ2000 PC

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**Purpose:** The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>1</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>0</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td>Inside the power supply. The quantity may vary.</td>
<td>4</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td>Power cord</td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants weighing &gt; 25 grams (not including PCBs or PCAs already listed as a separate item above)</td>
<td>Internal fans (2), external power supply (1)</td>
<td>3</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td></td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>

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PSG instructions for this template are available at [EL-MF877-01](EL-MF877-01)
Components, parts and materials containing radioactive substances 0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Philips Screwdriver</td>
<td></td>
</tr>
<tr>
<td>Flathead screwdriver</td>
<td></td>
</tr>
<tr>
<td>Knife</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Unfix system side cover screw*1 then remove side cover.
2. Remove front panel from system.
3. Displug all cable connector from motherboard and all devices. Remove the CPU fan
4. Unfix front IO cable screw*1 then remove it.
5. Unfix card reader screw*1 then remove it.
6. Unfix PSU screw*4 then remove it. Unsolder the capacitors and the PSU fan.
7. Remove Add-on card fixed bracket screw*1 then remove all add-on cards.
8. Unfix H/S screw*4 then remove it from MB
9. Unfix MB screw*8 then remove it from chassis
10. Remove coin cell battery on MB
11. Disassemble the power supply case

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

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1. Remove side cover

1. Unfix thumbscrew 1pcs.
2. Remove side cover

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2. Remove main bezel

1. Release main bezel hook 1, 2, 3.

2. Take out main bezel
3. Unplug all cable

Unplug:
1. Power cable (24pin)
2. Heat sink fan cable
3. 12V power cable (4pin)
4. Audio cable
5. Front USB, card reader and switch cable
6. HDD data cable
7. ODD data cable
4. Remove front I/O

1. Remove front I/O cable.
6. Remove PSU

1. Unfix 4 screw front chassis.
2. Remove PSU front chassis.

FIGURE 1. Unscrew from cover. (First side)
FIGURE 2. Unscrew from cover. (The other side)

FIGURE 3. Remove P2 Cable tie.

FIGURE 4. Remove O/P Cable tie.
FIGURE 5. Slide cover to the right.

FIGURE 6. Remove L/N from PCB
FIGURE 7. Remove Fan wire from PCB.

FIGURE 8. Unscrew & remove PCB from chassis.
FIGURE 9. Remove Electrolytic Capacitor
7. Remove Add-on card

1. Unfix 1 screw and remove fixed bracket
2. Press lock
3. Unplug VGA card
8. Remove Heat Sink

1. Unfix 4 screw front Heat Sink
2. Remove Heat Sink
9. Remove MB

1. Unfix 8 screw front chassis
2. Remove MB front chassis
8. Disassemble the power supply case parts.

Remove coin battery from MB